**Am27C256**

256 Kilobit (32,768 x 8-Bit) CMOS EPROM

**DISTINCTIVE CHARACTERISTICS**
- Fast access time — 55 ns
- Low power consumption — 20 μA typical CMOS standby current
- JEDEC-approved pinout
- Single +5 V power supply
- ±10% power supply tolerance available
- 100% Flashrite programming — Typical programming time of 4 seconds
- Latch-up protected to 100 mA from –1 V to Vcc + 1 V
- High noise immunity
- Versatile features for simple interfacing — Both CMOS and TTL input/output compatibility — Two line control functions
- Standard 28-pin DIP, PDIP, 32-pin TSOP and PLCC packages

**GENERAL DESCRIPTION**

The Am27C256 is a 256K-bit ultraviolet erasable programmable read-only memory. It is organized as 32K words by 8 bits per word, operates from a single +5 V supply, has a static standby mode, and features fast single address location programming. Products are available in windowed ceramic DIP packages as well as plastic one time programmable (OTP) PDIP, TSOP, and PLCC packages.

Typically, any byte can be accessed in less than 55 ns, allowing operation with high-performance microprocessors without any WAIT states. The Am27C256 offers separate Output Enable (OE) and Chip Enable (CE) controls, thus eliminating bus contention in a multiple bus microprocessor system.

AMD’s CMOS process technology provides high speed, low power, and high noise immunity. Typical power consumption is only 80 mW in active mode, and 100 μW in standby mode.

All signals are TTL levels, including programming signals. Bit locations may be programmed singly, in blocks, or at random. The Am27C256 supports AMD’s Flashrite programming algorithm (100 μs pulses) resulting in typical programming time of 4 seconds.

**BLOCK DIAGRAM**

[Diagram showing the internal block diagram of the Am27C256]
### PRODUCT SELECTOR GUIDE

<table>
<thead>
<tr>
<th>Family Part No.</th>
<th>Am27C256</th>
</tr>
</thead>
<tbody>
<tr>
<td>Ordering Part No:</td>
<td></td>
</tr>
<tr>
<td>VCC ± 5%</td>
<td>-55</td>
</tr>
<tr>
<td>VCC ± 10%</td>
<td>55</td>
</tr>
<tr>
<td>Max Access Time (ns)</td>
<td>55</td>
</tr>
<tr>
<td>CE (E) Access Time (ns)</td>
<td>55</td>
</tr>
<tr>
<td>OE (G) Access Time (ns)</td>
<td>35</td>
</tr>
</tbody>
</table>

### CONNECTION DIAGRAMS

#### Top View

**DIP**

- VPP 1
- A12 2
- A7 3
- A6 4
- A5 5
- A4 6
- A3 7
- A2 8
- A1 9
- A0 10
- DQ0 11
- DQ1 12
- DQ2 13
- VSS 14

- VCC 28
- A14 27
- A13 26
- A8 25
- A9 24
- A11 23
- OE (G) 22
- A10 21
- CE (E) 20
- DQ7 19
- DQ6 18
- DQ5 17
- DQ4 16
- DQ3 15

**PLCC**

- A7 1
- A12 2
- VPP 3
- DU 4
- A13 5
- CE (E) 29
- A8 28
- A11 27
- A10 26
- NC 25
- OE (G) 24
- A9 23
- A1 22
- A0 21
- DQ7 20
- DQ6 19
- VSS 18
- DQ5 17
- DQ4 16
- DQ3 15

#### Notes:
1. JEDEC nomenclature is in parentheses.
CONNECTION DIAGRAM

TSOP*

*Contact local AMD sales office for package availability

Standard Pinout

PIN DESIGNATIONS
A0–A14 = Address Inputs
\( \overline{CE} (E) \) = Chip Enable
DQ0–DQ7 = Data Inputs/Outputs
\( \overline{OE} (G) \) = Output Enable Input
V\( \text{CC} \) = V\( \text{CC} \) Supply Voltage
V\( \text{PP} \) = Program Voltage Input
V\( \text{SS} \) = Ground
DU = Don’t Use
ORDERING INFORMATION
UV EPROM Products
AMD Standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

- **DEVICE NUMBER**
  - Am27C256
  - 256 Kilobit (32,768 x 8-Bit) CMOS UV EPROM

- **VALID COMBINATIONS**
  - AM27C256-55
  - AM27C256-90
  - AM27C256-120
  - AM27C256-150
  - AM27C256-200
  - AM27C256-255
  - DC, DCB, DI, DIB

- **OPTIONAL PROCESSING**
  - Blank = Standard Processing
  - B = Burn-in

- **TEMPERATURE RANGE**
  - C = Commercial (0°C to +70°C)
  - I = Industrial (−40°C to +85°C)
  - E = Extended Commercial (−55°C to +125°C)

- **PACKAGE TYPE**
  - D = 28-Pin Ceramic DIP (CDV028)

- **SPEED OPTION**
  - See Product Selector Guide and Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.
ORDERING INFORMATION

OTP Products
AMD Standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

- **DEVICE NUMBER**
  - Am27C256
  - 256 Kilobit (32,768 x 8-Bit) CMOS OTP EPROM

- **OPTIONAL PROCESSING**
  - Blank = Standard Processing

- **TEMPERATURE RANGE**
  - C = Commercial (0°C to +70°C)
  - I = Industrial (–40°C to +85°C)

- **PACKAGE TYPE**
  - P = 28-Pin Plastic DIP (PD 028)
  - J = 32-Pin Rectangular Plastic Leaded Chip Carrier (PL 032)
  - E = 32-Pin TSOP (TS 032)

- **SPEED OPTION**
  - See Product Selector Guide and Valid Combinations

### Valid Combinations

<table>
<thead>
<tr>
<th>Valid Combinations</th>
<th>Options</th>
</tr>
</thead>
<tbody>
<tr>
<td>AM27C256-55</td>
<td>JC, PC, EC</td>
</tr>
<tr>
<td>AM27C256-70</td>
<td></td>
</tr>
<tr>
<td>AM27C256-90</td>
<td>JC, PC, EC, JI, PI, EI</td>
</tr>
<tr>
<td>AM27C256-120</td>
<td></td>
</tr>
<tr>
<td>AM27C256-150</td>
<td></td>
</tr>
<tr>
<td>AM27C256-200</td>
<td></td>
</tr>
<tr>
<td>AM27C256-255</td>
<td></td>
</tr>
</tbody>
</table>

**Valid Combinations**

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.
FUNCTIONAL DESCRIPTION

Erasing the Am27C256

In order to clear all locations of their programmed contents, it is necessary to expose the Am27C256 to an ultraviolet light source. A dosage of 15 W sec/cm² is required to completely erase an Am27C256. This dosage can be obtained by exposure to an ultraviolet amp—wavelength of 2537 Å—with intensity of 12,000 μW/cm² for 15 to 20 minutes. The Am27C256 should be directly under and about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the Am27C256 and similar devices will erase with light sources having wavelengths shorter than 4000 Å. Although erase times will be much longer than with UV sources at 2537 Å, exposure to fluorescent light and sunlight will eventually erase the Am27C256 and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package window should be covered by an opaque label or substance.

Programming the Am27C256

Upon delivery or after each erasure the Am27C256 has all 262,144 bits in the “ONE” or HIGH state. “ZEROs” are loaded into the Am27C256 through the procedure of programming.

The programming mode is entered when 12.75 V ± 0.25 V is applied to the Vpp pin, OE is at Vih, and CE is at VIL.

For programming, the data to be programmed is applied 8 bits in parallel to the data output pins.

The Flashrite algorithm reduces programming time by using 100 μs programming pulses and by giving each address only as many pulses as is necessary in order to reliably program the data. After each pulse is applied to a given address, the data in that address is verified. If the data does not verify, additional pulses are given until it verifies or the maximum is reached. This process is repeated while sequencing through each address of the Am27C256. This part of the algorithm is done at VCC = 6.25 V to assure that each EPROM bit is programmed to a sufficiently high threshold voltage. After the final address is completed, the entire EPROM memory is verified at VCC = Vpp = 5.25 V.

Please refer to Section 6 for programming flow chart and characteristics.

Program Inhibit

Programming of multiple Am27C256 in parallel with different data is also easily accomplished. Except for CE, all like inputs of the parallel Am27C256 may be common. A TTL low-level program pulse applied to an Am27C256 CE input with Vpp = 12.75 V ± 0.25 V, and OE High will program that Am27C256. A high-level CE input inhibits the other Am27C256 devices from being programmed.

Program Verify

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify should be performed with OE at Vil, CE at Vih, and VPP between 12.5 V to 13.0 V.

Auto Select Mode

The auto select mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmed with its corresponding programming algorithm. This mode is functional in the 25°C ± 5°C ambient temperature range that is required when programming the Am27C256.

To activate this mode, the programming equipment must force 12.0 V ± 0.5 V on address line A9 of the Am27C256. Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from Vil to Vih. All other address lines must be held at Vil during auto select mode.

Byte 0 (A0 = Vil) represents the manufacturer code, and byte 1 (A0 = Vih), the device code. For the Am27C256, these two identifier bytes are given in the Mode Select Table. All identifiers for manufacturer and device codes will possess odd parity, with the MSB (DQ7) defined as the parity bit.

Read Mode

The Am27C256 has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable (CE) is the power control and should be used for device selection. Output Enable (OE) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (tACC) is equal to the delay from CE to output (tOE). Data is available at the outputs toE after the falling edge of OE, assuming that CE has been LOW and addresses have been stable for at least tACC–tOE.

Standby Mode

The Am27C256 has a CMOS standby mode which reduces the maximum VCC current to 100 μA. It is placed in CMOS-standby when CE is at VCC ± 0.3 V. The Am27C256 also has a TTL-standby mode which reduces the maximum VCC current to 1.0 mA. It is placed in TTL-standby when CE is at Vih. When in standby mode, the outputs are in a high-impedance state, independent of the OE input.
Output OR-Tieing

To accommodate multiple memory connections, a two-line control function is provided to allow for:

- Low memory power dissipation
- Assurance that output bus contention will not occur

It is recommended that CE be decoded and used as the primary device-selecting function, while OE be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in low-power standby mode and that the output pins are only active when data is desired from a particular memory device.

System Applications

During the switch between active and standby conditions, transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a 0.1-μF ceramic capacitor (high frequency, low inherent inductance) should be used on each device between VCC and VSS to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a 4.7-μF bulk electrolytic capacitor should be used between VCC and VSS for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

MODE SELECT TABLE

<table>
<thead>
<tr>
<th>Mode</th>
<th>Pins</th>
<th>CE</th>
<th>OE</th>
<th>A0</th>
<th>A9</th>
<th>Vpp</th>
<th>Outputs</th>
</tr>
</thead>
<tbody>
<tr>
<td>Read</td>
<td></td>
<td>VIL</td>
<td>VIL</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>DOUT</td>
</tr>
<tr>
<td>Output Disable</td>
<td></td>
<td>X</td>
<td>VIH</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>High-Z</td>
</tr>
<tr>
<td>Standby (TTL)</td>
<td></td>
<td>VIH</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>High-Z</td>
</tr>
<tr>
<td>Standby (CMOS)</td>
<td></td>
<td>VCC ± 0.3 V</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>X</td>
<td>High-Z</td>
</tr>
<tr>
<td>Program</td>
<td></td>
<td>VIL</td>
<td>VIH</td>
<td>X</td>
<td>X</td>
<td>VPP</td>
<td>DIN</td>
</tr>
<tr>
<td>Program Verify</td>
<td></td>
<td>VIH</td>
<td>VIL</td>
<td>X</td>
<td>X</td>
<td>VPP</td>
<td>DOUT</td>
</tr>
<tr>
<td>Program Inhibit</td>
<td></td>
<td>VIH</td>
<td>VIH</td>
<td>X</td>
<td>X</td>
<td>VPP</td>
<td>High-Z</td>
</tr>
<tr>
<td>Auto Select</td>
<td></td>
<td>VIL</td>
<td>VIL</td>
<td>VIL</td>
<td>VH</td>
<td>X</td>
<td>01H</td>
</tr>
<tr>
<td>(Note 3) Manufacturer Code</td>
<td></td>
<td>VIL</td>
<td>VIL</td>
<td>VIL</td>
<td>VH</td>
<td>X</td>
<td>10H</td>
</tr>
<tr>
<td>Device Code</td>
<td></td>
<td>VIL</td>
<td>VIL</td>
<td>VIH</td>
<td>VH</td>
<td>X</td>
<td></td>
</tr>
</tbody>
</table>

Notes:
1. \( V_H = 12.0 \, V \pm 0.5 \, V \)
2. \( X = \text{Either} \, V_H \, \text{or} \, V_L \)
3. \( A1–A8 = A10–A14 = V_L \)
4. See DC Programming Characteristics for \( V_{PP} \) voltage during programming.
ABSOLUTE MAXIMUM RATINGS

Storage Temperature
- OTP Products: –65°C to +125°C
- All Other Products: –65°C to +150°C

Ambient Temperature with Power Applied
- OTP Products: –55°C to +125°C
- All Other Products: –55°C to +150°C

Voltage with Respect To VSS
- All pins except A9, VPP, VCC (Note 1): –0.6 V to VCC + 0.5 V
- A9 and VPP (Note 2): –0.6 V to +13.5 V
- VCC: –0.6 V to +7.0 V

Notes:
1. Minimum DC voltage on input or I/O pins is –0.5 V. During transitions, the inputs may overshoot VSS to –2.0 V for periods of up to 20 ns. Maximum DC voltage on input and I/O pins is VCC + 0.5 V which may overshoot to VCC + 2.0 V for periods up to 20 ns.
2. For A9 and VPP, the minimum DC input is –0.5 V. During transitions, A9 and VPP may overshoot VSS to –2.0 V for periods of up to 20 ns. A9 and VPP must not exceed 13.5 V for any period of time.

Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure of the device to absolute maximum rating conditions for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices
- Ambient Temperature (TA): 0°C to +70°C

Industrial (I) Devices
- Ambient Temperature (TA): –40°C to +85°C

Extended Commercial (E) Devices
- Ambient Temperature (TA): –55°C to +125°C

Supply Read Voltages
- VCC for Am27C256-XX5: +4.75 V to +5.25 V
- VCC for Am27C256-XX0: +4.50 V to +5.50 V

Operating ranges define those limits between which the functionality of the device is guaranteed.
DC CHARACTERISTICS over operating range unless otherwise specified.  
(Notes 1, 2 and 4)

<table>
<thead>
<tr>
<th>Parameter Symbol</th>
<th>Parameter Description</th>
<th>Test Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{OH}$</td>
<td>Output HIGH Voltage</td>
<td>$I_{OH} = -400 , \mu A$</td>
<td>2.4</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>$V_{OL}$</td>
<td>Output LOW Voltage</td>
<td>$I_{OL} = 2.1 , mA$</td>
<td></td>
<td>0.45</td>
<td>V</td>
</tr>
<tr>
<td>$V_{IH}$</td>
<td>Input HIGH Voltage</td>
<td></td>
<td>2.0</td>
<td>$V_{CC} + 0.5$</td>
<td>V</td>
</tr>
<tr>
<td>$V_{IL}$</td>
<td>Input LOW Voltage</td>
<td></td>
<td>$-0.5$</td>
<td>$+0.8$</td>
<td>V</td>
</tr>
<tr>
<td>$I_{L}$</td>
<td>Input Load Current</td>
<td>$V_{IN} = 0 , V$ to $+V_{CC}$</td>
<td>1.0</td>
<td></td>
<td>$\mu A$</td>
</tr>
<tr>
<td>$I_{LO}$</td>
<td>Output Leakage Current</td>
<td>$V_{OUT} = 0 , V$ to $+V_{CC}$</td>
<td></td>
<td>1.0</td>
<td>$\mu A$</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>$I_{CC1}$</td>
<td>$V_{CC}$ Active Current</td>
<td>$CE = V_{IL}$, $f = 10$ MHz, $I_{OUT} = 0$ mA</td>
<td>25</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>$I_{CC2}$</td>
<td>$V_{CC}$ TTL Standby Current</td>
<td>$CE = V_{IH}$</td>
<td>1.0</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>$I_{CC3}$</td>
<td>$V_{CC}$ CMOS Standby Current</td>
<td>$CE = V_{CC} \pm 0.3$ V</td>
<td>100</td>
<td></td>
<td>$\mu A$</td>
</tr>
<tr>
<td>$I_{PP1}$</td>
<td>VPP Current During Read</td>
<td>$CE = O_{E} = V_{IL}$, $V_{PP} = V_{CC}$</td>
<td>100</td>
<td></td>
<td>$\mu A$</td>
</tr>
</tbody>
</table>

Notes:
1. $V_{CC}$ must be applied simultaneously or before $V_{PP}$, and removed simultaneously or after $V_{PP}$.
2. **Caution:** The Am27C256 must not be removed from (or inserted into) a socket when $V_{CC}$ or $V_{PP}$ is applied.
3. $I_{CC1}$ is tested with $O_{E} = V_{IH}$ to simulate open outputs.
4. Minimum DC Input Voltage is $-0.5$ V. During transitions, the inputs may overshoot to $-2.0$ V for periods less than 20 ns. Maximum DC Voltage on output pins is $V_{CC} + 0.5$ V, which may overshoot to $V_{CC} + 2.0$ V for periods less than 20 ns.

![Figure 1. Typical Supply Current vs. Frequency](image1)

![Figure 2. Typical Supply Current vs. Temperature](image2)
### CAPACITANCE

<table>
<thead>
<tr>
<th>Parameter Symbol</th>
<th>Parameter Description</th>
<th>Test Conditions</th>
<th>CDV028</th>
<th>PL 032</th>
<th>PD 028</th>
<th>TS 028</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>CIN</td>
<td>Input Capacitance</td>
<td>$V_{IN} = 0$</td>
<td>8</td>
<td>12</td>
<td>8</td>
<td>10</td>
<td>12</td>
</tr>
<tr>
<td>COUT</td>
<td>Output Capacitance</td>
<td>$V_{OUT} = 0$</td>
<td>8</td>
<td>12</td>
<td>8</td>
<td>10</td>
<td>12</td>
</tr>
</tbody>
</table>

**Notes:**

1. This parameter is only sampled and not 100% tested.
2. $T_A = +25°C$, $f = 1$ MHz.

### SWITCHING CHARACTERISTICS over operating range unless otherwise specified (Notes 1, 3 and 4)

<table>
<thead>
<tr>
<th>Parameter Symbols</th>
<th>Parameter Description</th>
<th>Test Conditions</th>
<th>Am27C256</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>$V_{IL}$ = Min</td>
<td>$V_{IL}$ = Max</td>
</tr>
<tr>
<td>tAVQV</td>
<td>Address to CE</td>
<td>$CE = OE = V_{IL}$</td>
<td>$CE = OE = V_{IL}$</td>
</tr>
<tr>
<td>tELQV</td>
<td>Chip Enable to OE</td>
<td>$OE = V_{IL}$</td>
<td>$OE = V_{IL}$</td>
</tr>
<tr>
<td>tGLQV</td>
<td>Output Enable to CE</td>
<td>$OE = V_{IL}$</td>
<td>$OE = V_{IL}$</td>
</tr>
<tr>
<td>tEHQZ, tGHQZ</td>
<td>Chip Enable HIGH or OE</td>
<td>$OE = V_{IL}$</td>
<td>$OE = V_{IL}$</td>
</tr>
<tr>
<td>tAXQX</td>
<td>Output Hold from</td>
<td>$OE$</td>
<td>$OE$, whichever occurred first</td>
</tr>
</tbody>
</table>

**Notes:**

1. $V_{CC}$ must be applied simultaneously or before $V_{PP}$, and removed simultaneously or after $V_{PP}$.
2. This parameter is only sampled and not 100% tested.
3. Caution: The Am27C256 must not be removed from (or inserted into) a socket or board when $V_{PP}$ or $V_{CC}$ is applied.
4. For the -55 and -70:
   - Output Load: 1 TTL gate and $C_L = 30$ pF
   - Input Rise and Fall Times: 20 ns
   - Input Pulse Levels: 0 V to 3 V
   - Timing Measurement Reference Level: 1.5 V for inputs and outputs
   - For all other versions:
     - Output Load: 1 TTL gate and $C_L = 100$ pF
     - Input Rise and Fall Times: 20 ns
     - Input Pulse Levels: 0.45 V to 2.4 V
     - Timing Measurement Reference Level: 0.8 V and 2 V inputs and outputs

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Am27C256 2-41
SWITCHING TEST CIRCUIT

Device Under Test

\[ C_L = 100 \text{ pF including jig capacitance (30 pF for -55, -70)} \]

Diodes = IN3064 or Equivalent

SWITCHING TEST WAVEFORM

**AC Testing:** Inputs are driven at 2.4 V for a logic “1” and 0.45 V for a logic “0”. Input pulse rise and fall times are \( \leq 20 \text{ ns} \).

AC Testing: Inputs are driven at 3.0 V for a logic “1” and 0 V for a logic “0”. Input pulse rise and fall times are \( \leq 20 \text{ ns} \) for -55 and -70.
KEY TO SWITCHING TEST WAVEFORMS

<table>
<thead>
<tr>
<th>WAVEFORM</th>
<th>INPUTS</th>
<th>OUTPUTS</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Must Be Steady</td>
<td>Will Be Steady</td>
</tr>
<tr>
<td></td>
<td>May Change from H to L</td>
<td>Will Be Changing from H to L</td>
</tr>
<tr>
<td></td>
<td>May Change from L to H</td>
<td>Will Be Changing from L to H</td>
</tr>
<tr>
<td></td>
<td>Don’t Care, Any Change Permitted</td>
<td>Changing State Unknown</td>
</tr>
<tr>
<td></td>
<td>Does Not Apply</td>
<td>Center Line is High Impedence “Off” State</td>
</tr>
</tbody>
</table>

SWITCHING WAVEFORMS

Notes:
1. $\overline{OE}$ may be delayed up to $t_{ACC} - t_{OE}$ after the falling edge of the addresses without impact on $t_{ACC}$.
2. $t_{DF}$ is specified from $OE$ or $CE$, whichever occurs first.